

LISTING OF CLAIMS:

1. (currently amended) A method of preparing a parametric speaker transducer for ~~(i) generating sonic or subsonic audio output by propagating two frequencies having a difference in value equal to the desired sonic or subsonic audio output and (ii) decoupling the two frequencies to generate the desired audio output~~, the method comprising the steps of:

- ~~a.~~ positioning an electrically sensitive, mechanically responsive film over at least one closed-end cavity of a rigid support member ~~within a pressure chamber~~;
- ~~b.~~ applying a pressure differential between that within the chamber cavity and ambient pressure to provide a ~~common~~ cavity pressure substantially different from ambient pressure; c. sealing the film to the support member ~~while within the pressure chamber~~ to capture the air in the cavity at the pressure differential in a permanent sealed configuration; and ,
- d. ~~removing the sealed film and support member from the pressure chamber, thereby~~ distending the film into an arcuate emitter configuration ~~with respect to the at least one cavity in response to the~~ a pressure differential between cavity pressure and ambient pressure on opposing sides of the film, to enable constricting and extending of the arcuate emitter configuration in response to variations in an applied electrical input at the piezoelectric film to thereby create a compression wave parametric output in a surrounding environment.

2. (withdrawn - currently amended) A method for making a speaker transducer for parametric sound reproduction ~~emitting subsonic, sonic or ultrasonic compression waves~~, said method comprising the steps of:

providing a piezoelectric film having conductive material applied to a front and a back surface thereof;

providing a rigid support member having at least one closed-end cavity formed therein;

a. positioning ~~the~~ a piezoelectric film over the at least one closed-end cavity within a rigid support member, said support member having an outer face formed around the at least one cavity;

~~b.~~ distending the piezoelectric film into an arcuate emitter configuration with respect to

the at least one cavity in response to a pressure differential between cavity pressure and ambient pressure on opposing sides of the film to enable constricting and extending of the emitter configuration in response to variations in an applied electrical input at the piezoelectric film to thereby create a parametric output ~~compression wave~~ in a surrounding environment; and e. ~~applying electrical input to the piezoelectric film to propagate a desired compression wave.~~

3. (withdrawn) A method as defined in claim 2, wherein the step of distending the film into the arcuate emitter configuration comprises the more specific steps of: a. positioning the support member and the piezoelectric film within a chamber having a chamber pressure at a substantial pressure differential with respect to ambient pressure; b. sealing the film to the outer face of the support member while in the chamber to capture the chamber pressure within the at least one cavity; and c. removing the support member and sealed film from the chamber to an ambient pressure environment to thereby distend the film into the arcuate configuration with respect to the at least one cavity.

4. (withdrawn) A method as defined in claim 3, comprising the more specific step of developing a negative pressure within the chamber, thereby creating a negative cavity pressure to distend the film into the arcuate configuration within the at least one cavity.

5. (withdrawn) A method as defined in claim 4, wherein the negative pressure approximately corresponds to a vacuum.

6. (withdrawn) A method as defined in claim 3, comprising the more specific step of developing a positive pressure within the chamber, thereby creating a positive cavity pressure to distend the film into the arcuate configuration away from the at least one cavity.

7. (withdrawn) A method as defined in claim 3, comprising the more specific step of positioning the support member and the piezoelectric film in a spatially separated configuration within the chamber having a chamber pressure at a substantial pressure differential with respect to ambient

pressure.

8. (withdrawn - currently amended) A method of making a parametric speaker transducer for emitting subsonic, sonic and ~~or~~ ultrasonic compression waves in a parametric output, said method comprising the steps of: a. positioning a piezoelectric film over an array of closed-end cavities formed within a rigid support member, said support member having an outer face formed around the array of cavities; b. distending the piezoelectric film into an arcuate emitter configuration with respect to the cavities in response to a pressure differential between cavity pressure and ambient pressure on opposing sides of the film to enable constricting and extending of the emitter configuration in response to variations in an applied electrical input at the piezoelectric film to thereby create a compression wave in a surrounding environment; and c. providing for applying an electrical input to the piezoelectric film to propagate a desired compression wave.

9. (withdrawn) A method as defined in claim 8, wherein the step of distending the film into an arcuate emitter configuration comprises the more specific steps of: a. positioning the support member and the piezoelectric film within a chamber having a chamber pressure at a substantial pressure differential with respect to ambient pressure; b. sealing the film to the outer face of the support member while in the chamber to capture the chamber pressure within the cavities; and c. removing the support member and sealed film from the chamber to an ambient pressure environment to thereby distend the film into the arcuate configuration with respect to the cavities.

10. (withdrawn) A method as defined in claim 9, comprising the more specific step developing a negative pressure within the chamber, thereby creating a negative cavity pressure to distend the film into the arcuate configuration within the at least one cavity.

11. (withdrawn) A method as defined in claim 9, comprising the more specific step of positioning the support member and the piezoelectric film in a spatially separated configuration

within the chamber having a chamber pressure at a substantial pressure differential with respect to ambient pressure.

12. (original) A method as defined in claim 1, further comprising the step of forming the at least one cavity in a circular configuration.

13. (original) A method as defined in claim 1, further comprising the step of forming the at least one cavity in an elliptical configuration.

14. (original) A method as defined in claim 1, further comprising the step of forming the at least one cavity in an elongated slot configuration.

15. (original) A method as defined in claim 1, further comprising the step of forming the at least one cavity in a serpentine configuration.

16. (original) A method as defined in claim 1, further comprising the step of forming the at least one cavity in a spiral configuration.

17. (original) A method as defined in claim 1, further comprising the step of forming the at least one cavity as an array of cavities forming a concentric configuration of rings.

18. (original) A method as defined in claim 1, wherein the step of applying an electrical input comprises the more specific step of applying an ultrasonic parametric signal capable of decoupling when emitted in air to generate a sonic compression wave as part of a parametric speaker system.

19. (original) A method as defined in claim 18, further comprising the step of optimizing the cavity configuration to have a resonant frequency coordinated with a carrier frequency of the ultrasonic parametric signal.

20. (original) A method as defined in claim 1, comprising the more specific steps of: a. positioning piezoelectric film over opposing closed-end cavities on opposing sides of and within a single rigid support member; b. distending the piezoelectric film into an arcuate emitter configuration with respect to the opposing cavities in response to a pressure differential between cavity pressure and ambient pressure on opposing sides of the film at each cavity to enable constricting and extending of the emitter configuration in response to variations in an applied electrical input at the piezoelectric film to thereby create opposing compression waves in a surrounding environment; and c. applying electrical input to the piezoelectric film to propagate the desired compression waves in opposing directions.

21. (original) A method as defined in claim 20, wherein the step of distending the film into the arcuate emitter configuration comprises the more specific steps of: a. positioning the support member and the piezoelectric film within a chamber having a chamber pressure at a substantial pressure differential with respect to ambient pressure; b. sealing the film to opposing outer faces of the support member while in the chamber to capture the chamber pressure within the opposing cavities on each face of the support member; and c. removing the support member and sealed film from the chamber to an ambient pressure environment to thereby distend the film into the arcuate configuration with respect to the cavities.

22. (original) A method as defined in claim 20, further comprising the steps of forming apertures in the support member with terminal openings exposed on opposing sides of the support member and applying the film over opposing sides of the support member to form the closed-end cavities over respective ends of the apertures.

23. (original) A method as defined in claim 1, wherein the step of distending the film into the arcuate emitter configuration comprises the more specific steps of: a. positioning the piezoelectric film on the support member prior to placement within a the pressure chamber and modifying chamber pressure to a substantial pressure differential with respect to ambient

pressure; b. sealing the film to the outer face of the support member while in the chamber to capture the modified chamber pressure within the at least one cavity; and c. removing the support member and sealed film from the chamber to an ambient pressure environment to thereby distend the film into the arcuate configuration with respect to the at least one cavity.

24. (withdrawn) A method as defined in claim 2, further comprising the applying heat to the film after sealing at the support member.

25. (withdrawn - currently amended) A method as defined in claim 2, wherein the step method of applying electrical signal input is accomplished as part of a parametric sound emitter configured for generating ~~near-field applications~~ of sonic energy for ~~direct~~ exposure to listeners

26. (withdrawn - currently amended) A method as defined in claim 2, wherein the step method of applying electrical signal input is accomplished as part of a parametric sound emitter configured for generating ~~far-field applications~~ of sonic energy for indirect exposure to listeners by way of a virtual speaker location at a reflective surface.

27. (withdrawn) A method as defined in claim 2, further comprising the step of directing the output of the emitter with low frequency emissions directly at an individual for physically disabling the individual.

28. (original) A method as defined in claim 1, comprising the more specific step of forming the closed-end cavity as a depression extending within but not through the support member.

29. (original) A method as defined in claim 1, comprising the more specific step of forming the closed-end cavity as a combination of at least one aperture through the support member communicating to an otherwise closed plenum chamber

30. (withdrawn - currently amended) A method of forming ~~protuberances in piezoelectric~~

~~material as a parametric emitter for an acoustic device~~, said method comprising the steps of: a. providing a substrate having a plurality of closed-end cavities of a given dimension formed therein; b. forming a laminate comprising a film of polymer piezoelectric material sandwiched between a first electrode layer on a top surface and a second electrode layer on a bottom surface of the polymer material; c. positioning the substrate and the laminate within a low pressure environment; d. securing the laminate to the substrate within the low pressure environment to form a sealed composite assembly which captures a low pressure state within the cavity between the substrate and the laminate; and e. positioning the composite assembly in an ambient pressure environment to form protuberances in the film at the locations of the perforations.

31. (withdrawn) The method of claim 30 further comprising the step of applying heat to the substructure and bonded piezoelectric film to accelerate the plurality of arcuate configurations to distend to a level of substantial stasis.

32. (withdrawn) The method of claim 30 further comprising the step of applying heat to the substructure and bonded piezoelectric film to accelerate the bonding of the piezoelectric film to the substructure.

33. (withdrawn) The method of claim 30 further comprising the step of sizing the plurality of cavities to form a resonance at a predetermined frequency.

34. (withdrawn) The method of claim 30 further comprising the step of forming electrical connectivity to the first electrode layer of the piezoelectric film and the second electrode layer of the piezoelectric film for coupling to an electrical signal source.

35. (withdrawn) A method as defined in claim 30, further comprising the steps a. providing a second emitter substructure having an outer face oriented outward in a different direction than the outer face of the first substructure and having a plurality of closed-end cavities formed thereon; b. providing a second piezoelectric film with a first conductive side and a second

conductive side with the second film prepared to be adhered at the second side to the second substructure outer face; c. placing the first and second piezoelectric films and the first and second emitter substructures in a vacuum chamber and substantially evacuating the air from the vacuum chamber; d. bonding the first and second piezoelectric films to outer faces of the first and second substructures within the evacuated vacuum chamber to capture a low pressure condition in the cavities enclosed by the films and substructures; e. removing the substructures and bonded piezoelectric films to be exposed to the external environment to allow atmospheric pressure to distend the piezoelectric thin films into concave arcuate configurations over the cavities; and f. applying electrical input to both the first and second films to simultaneously generate compression waves in two different directions.

36. (withdrawn - currently amended) A method for constructing a piezoelectric emitter comprising: a. providing an emitter substructure having at least one outer face having a closed-end cavity formed thereon; b. providing a piezoelectric film with a first conductive side and a second conductive side with the film prepared to be attached to the substructure outer face; c. placing the piezoelectric film and the emitter substructure in a vacuum chamber and substantially evacuating the air from the vacuum chamber; d. bonding the piezoelectric film to at least one outer face of the substructure with the vacuum chamber in a low pressure state; e. removing the substructure and bonded piezoelectric film to be exposed to the external environment to allow atmospheric pressure to distend the piezoelectric thin film into a concave arcuate region over the area of the cavity so the emitter can be used to generate a parametric output.

37. (withdrawn - currently amended) A method for constructing a piezoelectric emitter comprising: a. providing an emitter plate having at least one outer face oriented outward and at least one inner face with at least one cavity extending between the outer and inner faces; b. positioning a back cover against the inner face of the emitter plate to form a closed-cavity with the inner face being sealed off in relationship with the external environment; c. providing a piezoelectric film with a first conductive side and a second conductive side with the film prepared to be attached to the emitter plate outer face; d. placing the piezoelectric film and the

emitter plate in a vacuum chamber and substantially evacuating the air from the vacuum chamber to a low pressure state; e. bonding the piezoelectric film to outer face of the emitter plate to seal the cavity with a cavity pressure at the low pressure state; f. removing the substructure and bonded piezoelectric film to be exposed to the external environment to allow atmospheric pressure to distend the piezoelectric thin film into a concave arcuate region over the area of the cavity so the emitter can be used to generate a parametric output.